

Infonote

AO-IN-2026-015-I

Adding supplementary bump bond
on stitch for:

SFH 2700_A01

SFH 2700FA_A01

SFH 2711_A01

SFH 2716_A01

SFH 2770_A01

SFH 3716

SFH 5711

31.03.2026

Dear Customer,

Please take note of this **Infonote**.

This customer notification is for information only and does not require customer approval.

Objective: Adding supplementary bump bond on stitch for SFH 2700_A01, SFH 2700FA_A01, SFH 2711_A01, SFH 2716_A01, SFH 2770_A01, SFH 3716 and SFH 5711.

Affected products: SFH 2700_A01, SFH 2700FA_A01, SFH 2711_A01, SFH 2716_A01, SFH 2770_A01, SFH 3716 and SFH 5711.

Reason for change: Harmonization of wire bond process within the production line.
Improvement of package robustness against external mechanical influence.

| | <u>Current status</u> | <u>New status</u> |
|-------------------------------|--------------------------------------|-----------------------------------|
| Description of change: | No Supplementary bump bond on stitch | Supplementary bump bond on stitch |

Time schedule: Mid of April 2026 or DC 2616

Assessment: **No Change in fit, form and function.**
